

Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

What is claimed is:

Claim 1 (original): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit

components;

depositing a crossover circuit trace over the sacrificial material, the crossover circuit trace crossing over the circuit components; and

thermally decomposing the sacrificial material.

Claim 2 (withdrawn)

Claim 3 (original): The air bridge of claim 1, wherein the sacrificial material comprises polynorbornene.

Claim 4 (original): The air bridge of claim 1, wherein the one or more circuit components comprise a circuit trace.

Claim 5 (original): The air bridge of claim 4, wherein the circuit trace comprises a signal trace.

Claim 6 (original): The air bridge of claim 4, wherein the circuit trace comprises a ground trace.

Claim 7 (original): The air bridge of claim 4, wherein the circuit trace comprises a power trace.

Claim 8 (original): The air bridge of claim 1, wherein the crossover circuit trace comprises a signal trace.

Claims 9 – 20 (canceled)

Claim 21 (new): An air bridge produced by:

- depositing one or more circuit components on a substrate;
- depositing a sacrificial material over at least a portion of the circuit components;
- depositing a crossover circuit trace over the sacrificial material, the crossover circuit trace crossing over the circuit components and being directly supported by the substrate on opposite sides of the sacrificial material; and
- thermally decomposing the sacrificial material.

Claim 22 (new): The air bridge of claim, wherein depositing a sacrificial material comprises depositing the sacrificial material in a manner causing the sacrificial material to be dome shaped.

Claim 23 (new): The air bridge of claim 21, wherein the sacrificial material comprises polynorbornene.

Claim 24 (new): The air bridge of claim 21, wherein the one or more circuit components comprise a circuit trace.

Claim 25 (new): The air bridge of claim 24, wherein the circuit trace comprises a signal trace.

Claim 26 (new): The air bridge of claim 24, wherein the circuit trace comprises a ground trace.

Claim 27 (new): The air bridge of claim 24, wherein the circuit trace comprises a power trace.

Claim 28 (new): The air bridge of claim 21, wherein the crossover circuit trace comprises a signal trace.